ESDLC12VD3B

Description

Features

Ultra low leakage: nA level Operating voltage: 12V Package: SOD-323

Low clamping voltage

Air discharge: ±15kV

Contact discharge: ±8kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

- IEC61000-4-5 (Lightning) 12A (8/20µs)

Protects one I/O line (unidirection)

Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

ESDLC12VD3B is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, ultra-low capacitance values, it is very suitable for signal port and board space speed transmission is very small places, such as Ethernet, mobile phones, MP3 players, digital cameras and other portable.

Functional Diagram

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- USB Interface

Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

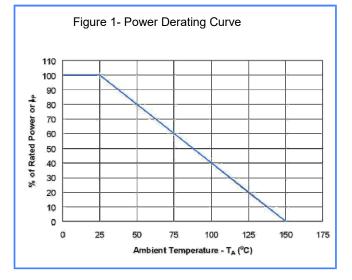
Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ppp	350	Watts	
ESD per IEC 61000-4-2 (Air)	N/	±15	KV	
ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±8	KV	
Lead Soldering Temperature	T∟	260 (10 sec)	°C	
Operating Temperature Range	TJ	-55 to +150	°C	
Storage Temperature Range	Т _{sтj}	-55 to +150	°C	

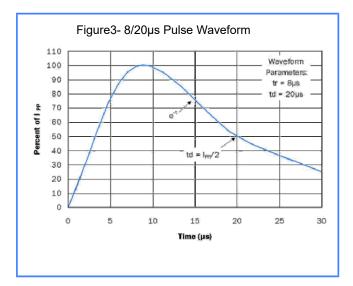
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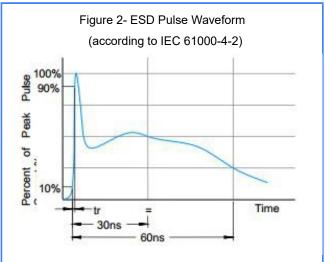
Electrical Characteristics (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-off Voltage	V _{RWM}				12	V
Reverse Breakdown Voltage	V _{br}	I _t = 1mA		13.3		V
Reverse Leakage Current	I _R	V _R =V _{RWM}			1	μA
Clamping Voltage	Vc	I _{₽₽} =1A, t _₽ = 8/20µs			19	V
		I _{₽₽} =7A, t _₽ = 8/20μs			30	V
Junction Capacitance	C	V _R =0V, f = 1MHz		1		pF

Characteristics Curves







Dated:04/2019 Rev: 1.0

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Package Outline

millimeters (inches)

